

1. Purpose of the call for papers

As part of the SLAM Conference 2026, which will take place from 25 to 27 November, the organisers (IFTEC, Inventec Performance Chemicals and We Network) are issuing a call for papers to select the technical contributions that will be presented during the conference.

Submitted proposals will be reviewed by the Technical Committee based on their technical quality, relevance and contribution to the current challenges facing the electronics industry.

The aim of the organisers and the Technical Committee is to build a state-of-the-art conference programme reflecting the latest expertise, technologies and industrial challenges across the entire electronic board value chain, from design to finished products.

2. Conference Tracks

Every contribution must fit within one of the following six technical tracks:

Design

- Topics related to the hardware design of printed circuit boards and DFX approaches: design for manufacturing, assembly, testing, reliability and durability, in industrial contexts with high quality and performance requirements.

PCBs and Substrates

- PCB technologies, advanced substrates, materials, architectures, manufacturing processes, miniaturisation, high density, thermal management and performance constraints.

Assembly Process

- Electronic assembly processes, soldering, component placement, cleaning, protection, automation, process control, and associated materials and equipment.

Testing, Inspection and Smart Factory

- Testing methods, inspection, quality control, traceability, digitalisation, automation, industrial data, AI, process monitoring.

Reliability and Quality of Assemblies

- Failure analysis, qualification, ageing, robustness, standards, risk management, product quality, environmental constraints and application requirements.

Sustainability and Circularity

- Eco-design, reduction of environmental impact, reparability, recyclability, material circularity, sustainable manufacturing, regulatory compliance and life cycle assesment.

3. Expected contributions

Contributions should adopt a technical, educational and well-documented approach.

They should place the topic presented within the broader context of the French and European electronics sector, highlighting the challenges it addresses as well as the added value that the proposed expertise or technical advancement can bring to the printed circuit board ecosystem.

Oral presentations are primarily intended for industry stakeholders, whilst academic contributions may be submitted in poster format and featured in dedicated pitch sessions. However, if an academic contribution is of technical relevance or particular interest to the sector, the Technical Committee may decide to accept it as a conference presentation.

Commercial or promotional presentations will not be accepted.

4. Format et éléments requis

For oral presentations, certain details will be requested on the application form:

- Title: Concise, representative of the content and without abbreviations
- Theme: The proposal must fall within one of the programme's six themes
- Authors and co-authors: Surname, first name and company
- Abstract of no more than 350 words
- A PDF document providing further details, sources, illustrations, figures or experimental results.

Authors are encouraged to outline the context and key issues relating to the proposed topic.

5. Submission Process and Deadlines

Any author wishing to submit an abstract must create a deposit account via the website slam-conference-electronique.fr under the 'Call for Papers' section.

Abstracts submitted by email will not be considered.

Call for Papers opens: **26 mai 2026**

Submission Deadline: **04 septembre 2026**

The technical committee is organised by theme. Each theme is supervised by at least two members of the technical committee, who will review the submitted abstracts and any supporting documents provided, and will jointly decide whether to accept or reject the abstract. They may contact the authors if they have any further questions.

Authors will be notified of the outcome of the review process after the submission deadline, and the final conference programme will be published in early September 2026.

**If you have any questions or would like further
information, please contact us at
inscriptions@slam-conference-electronique.fr**

SLAM conference is an event organized by



supported by



From the 25th to the 27th november 2026 in Angers